

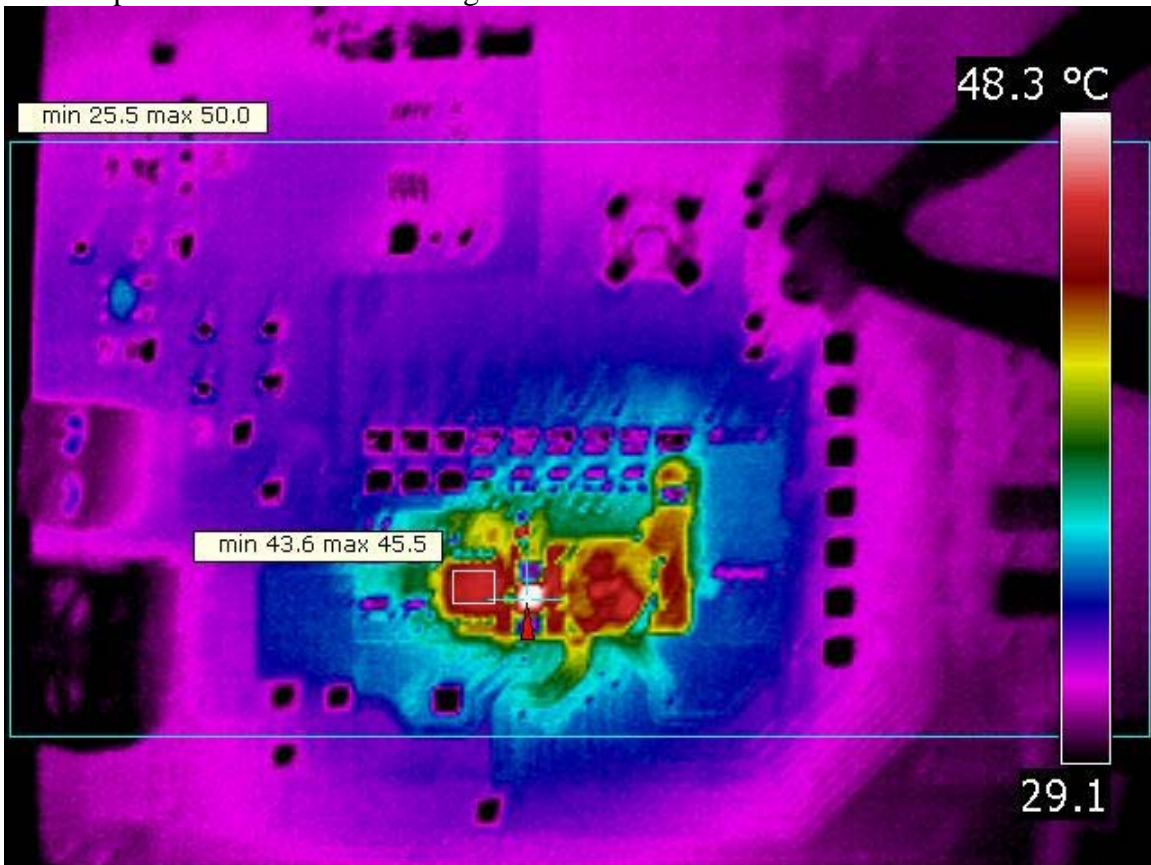
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Note: Main switch Q1 CSD86330Q3D is actually rated to 25Vds, not 30Vds. Hence, operation off inputs above 15V is not recommended.

Thermal:

PMP5486: 14.14Vin 411mAin 0.965Vout 5.00A 500kHz  
snubber hot at 50; dual FET CSD86330Q3 at 45.5  
choke top at 46 ambient at 23-25 degrees C



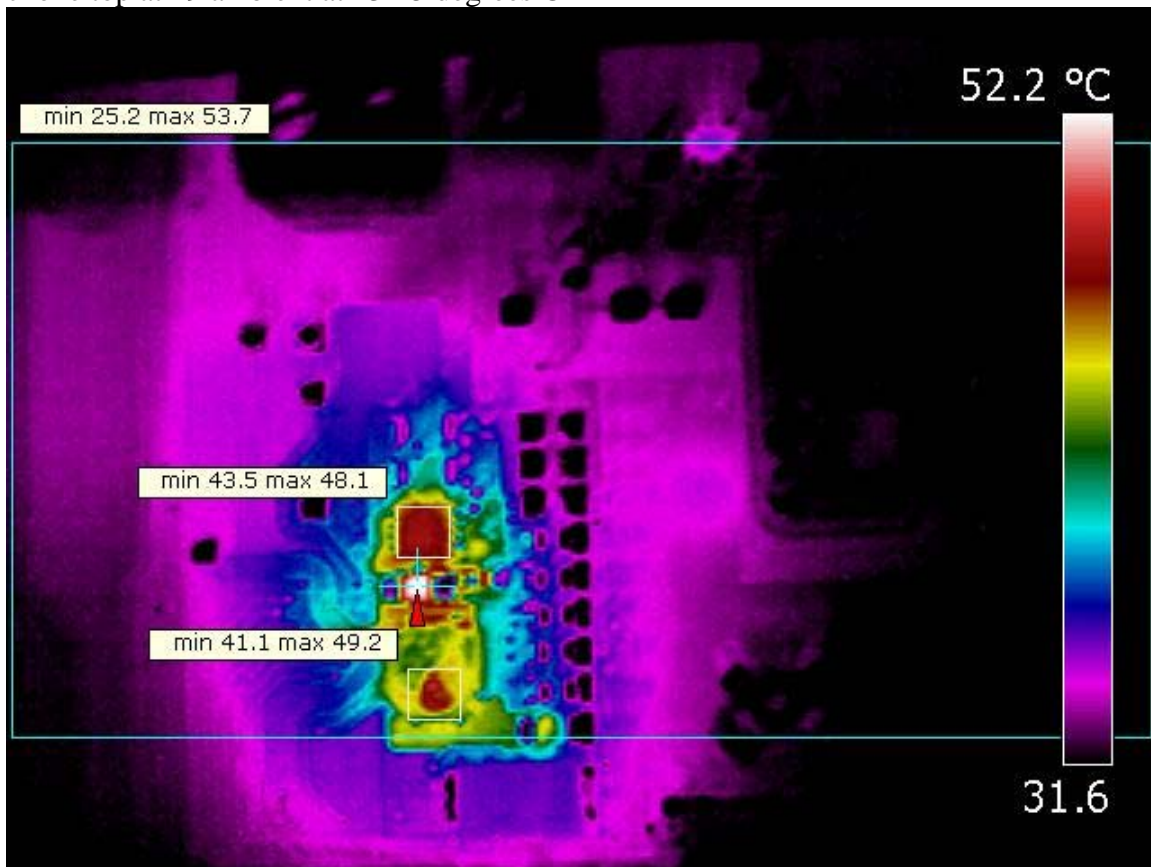
Qq  
Qq

19Vin thermal model T3:

PMP5486: 19Vin 315mAin 0.969Vout 5.00A 500kHz model t3

snubber hot at 54; dual FET CSD86330Q3 at 48

choke top at 49 ambient at 23-25 degrees C

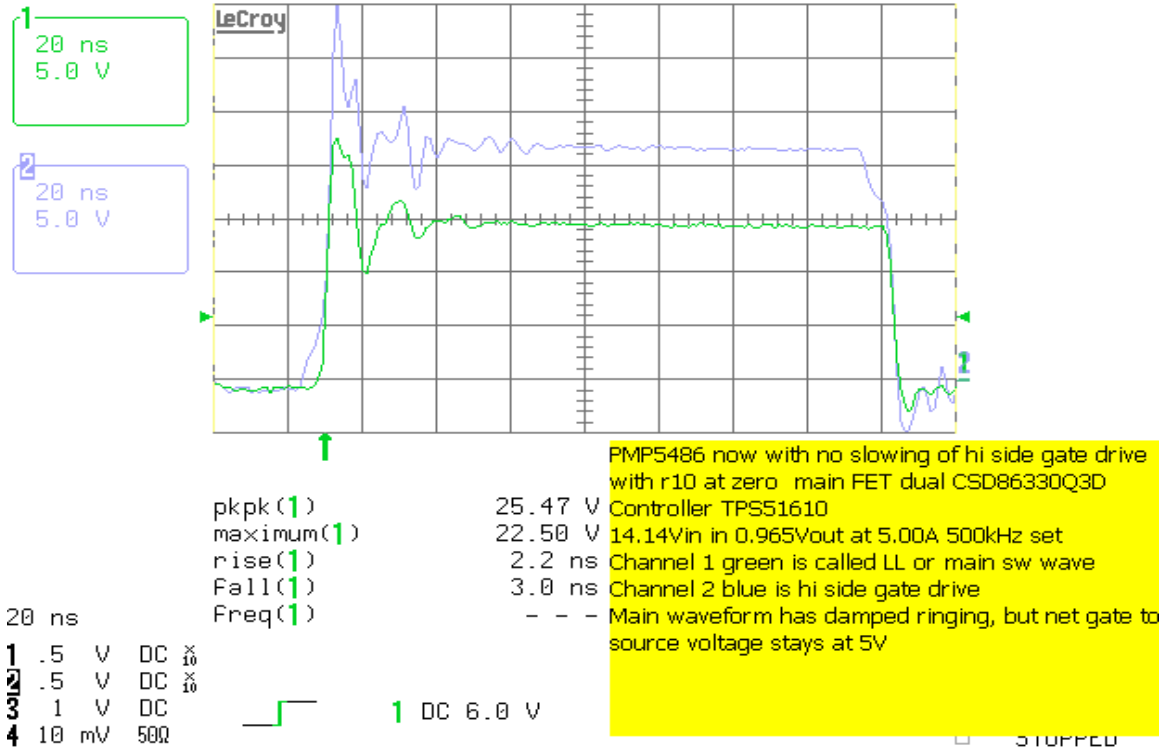


Qq

Note: Main switch Q1 CSD86330Q3D is actually rated to 25Vds, not 30Vds. Hence, operation off inputs above 15V is not recommended.

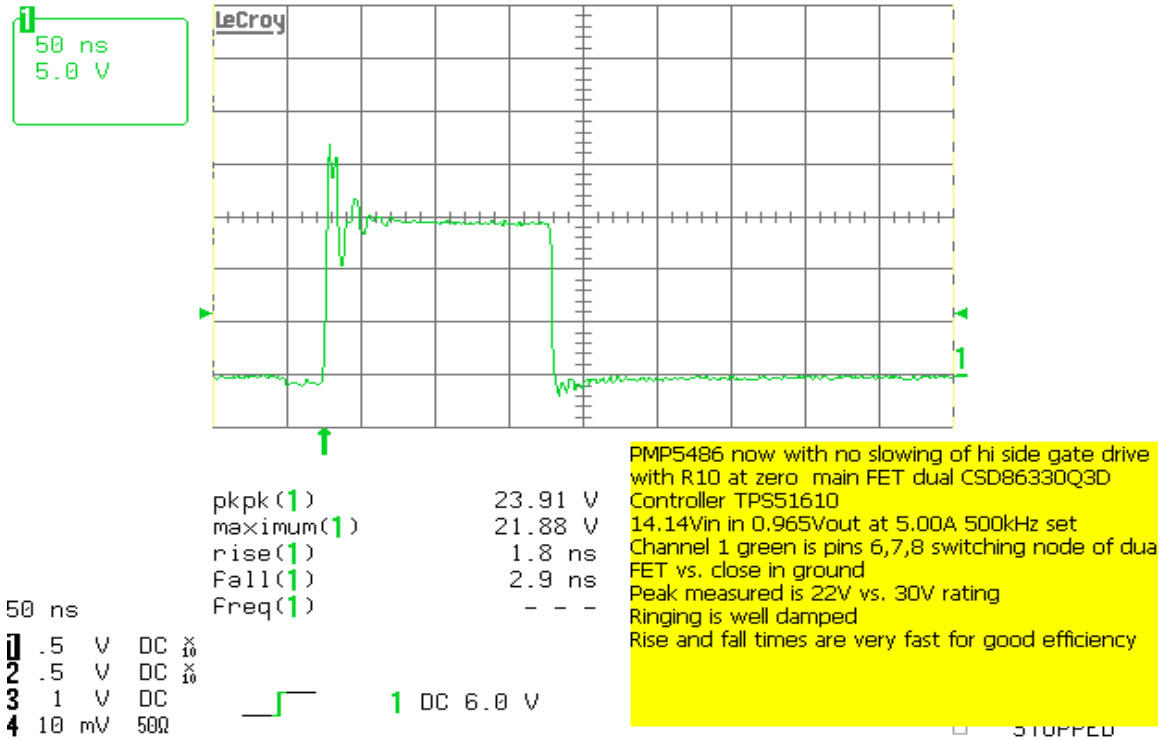
Main waveforms with 14Vin and 5A load: Model T1

17-Jun-10  
18:31:36



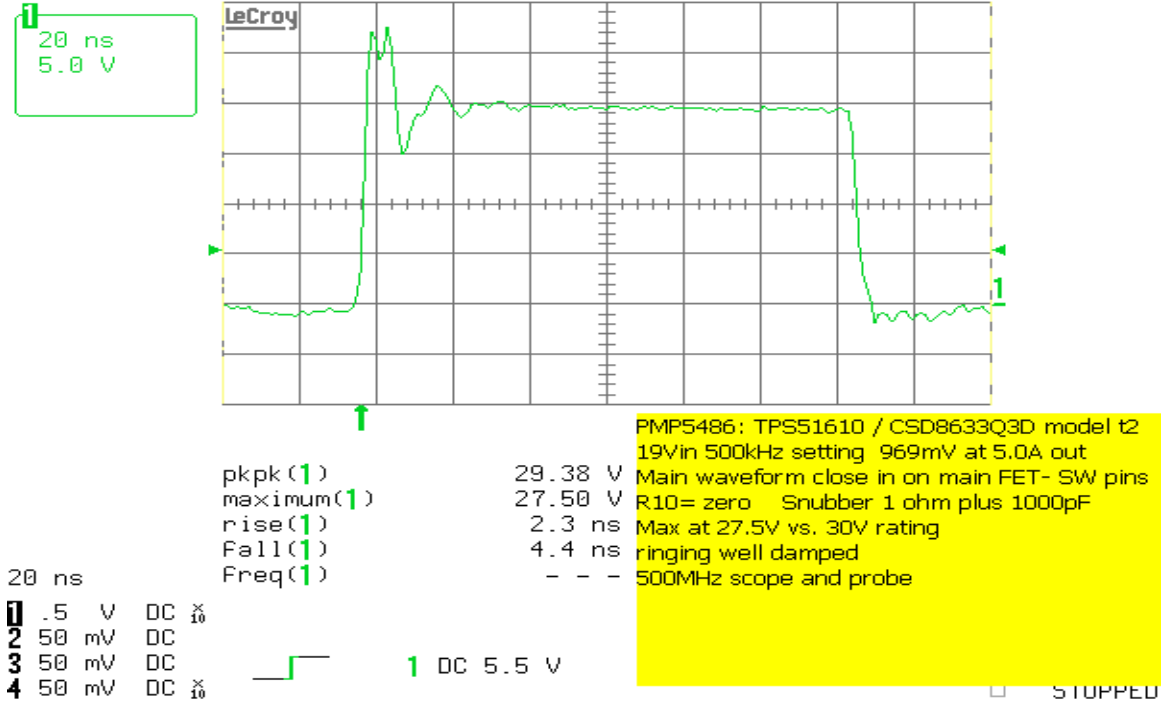
Now close in probe of just Vds of low side FET when hi side turns on:

17-Jun-10  
18:36:19



Main waveform: 19Vin model T2

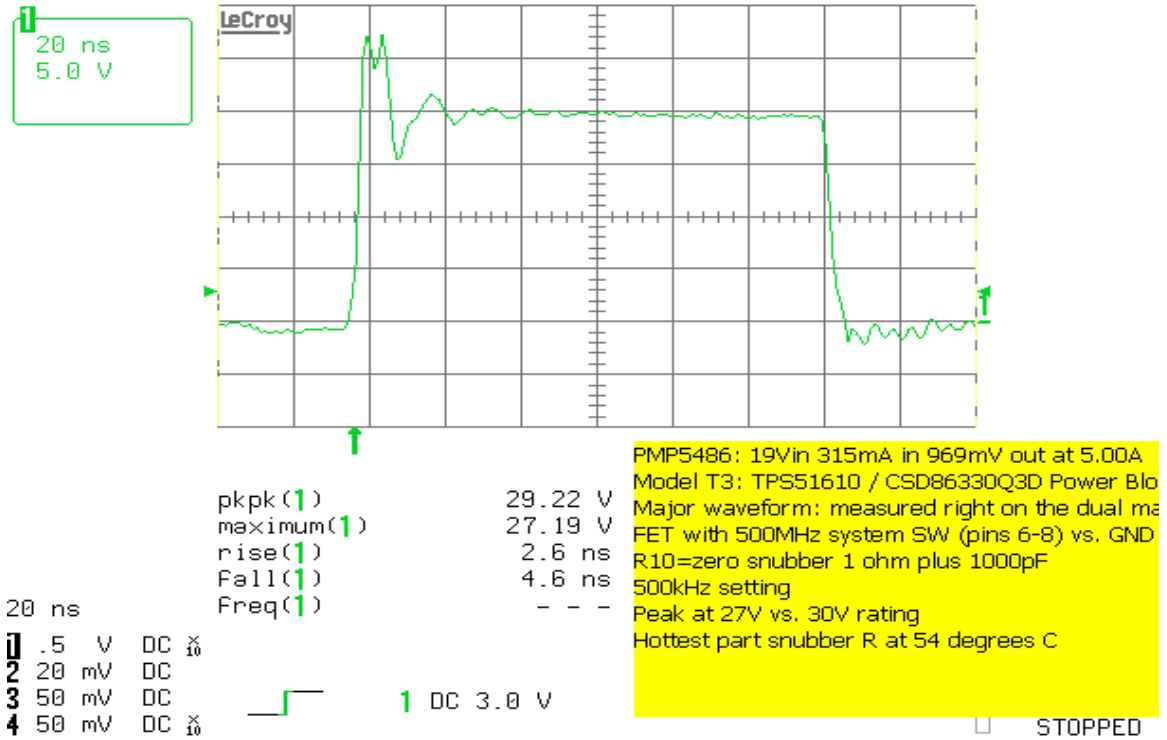
21-Jun-10  
16:54:43



Same with model T3:

22-Jun-10  
14:39:43

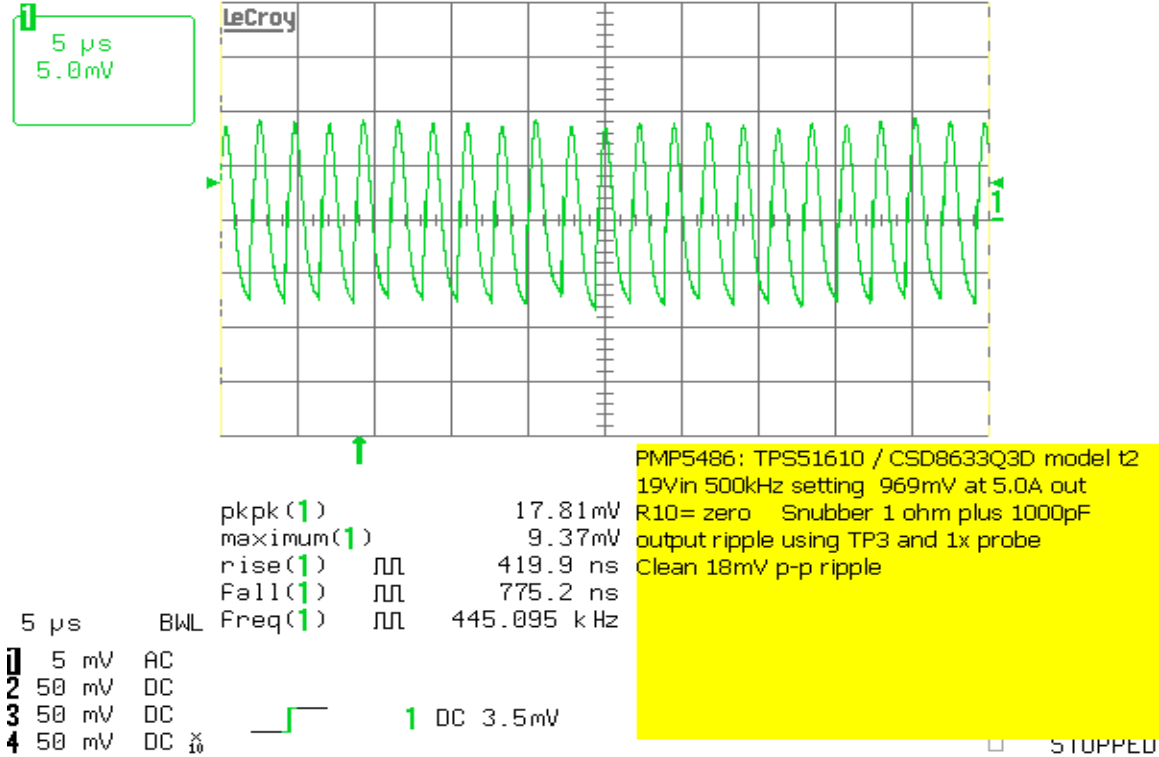
Reading Floppy Disk Drive



Qq

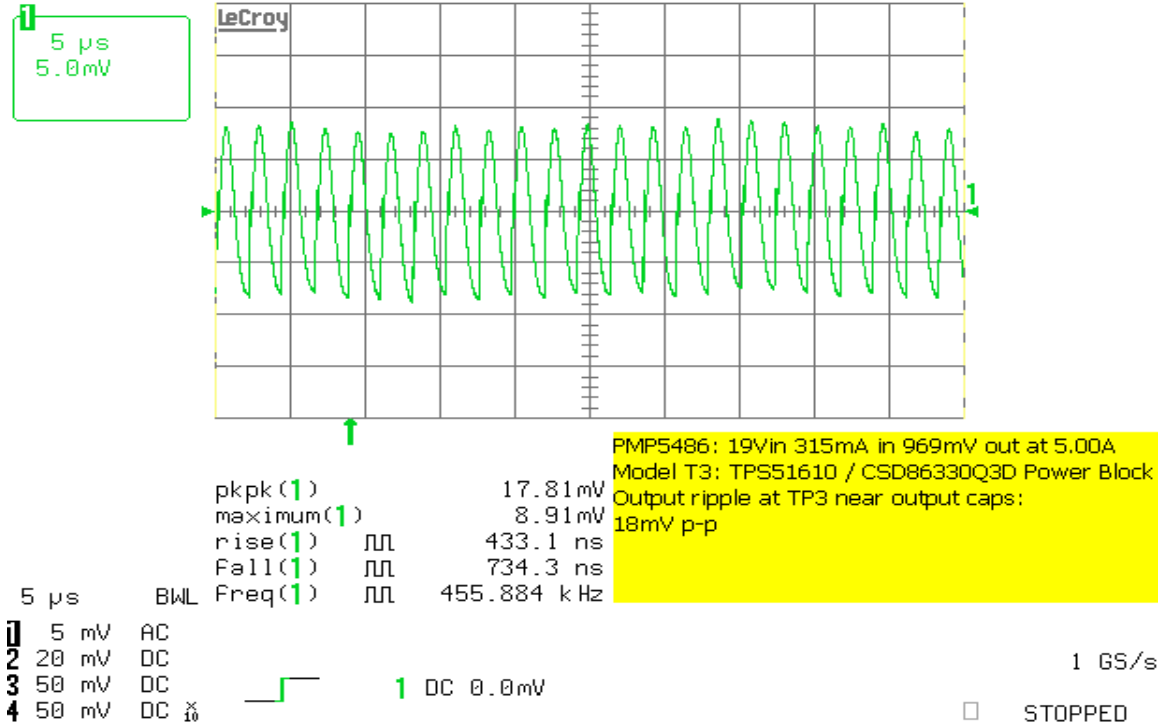
Output ripple: 19vin full load model T2

21-Jun-10  
17:02:14



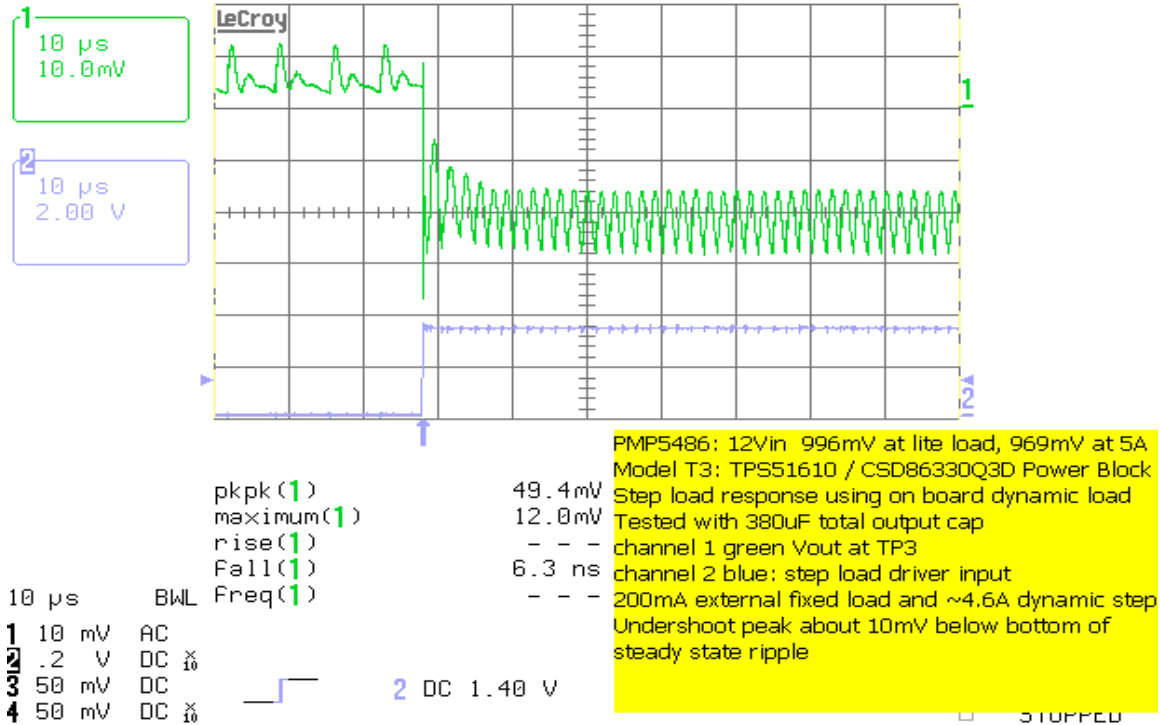
Same, but model T3:

22-Jun-10  
14:42:45



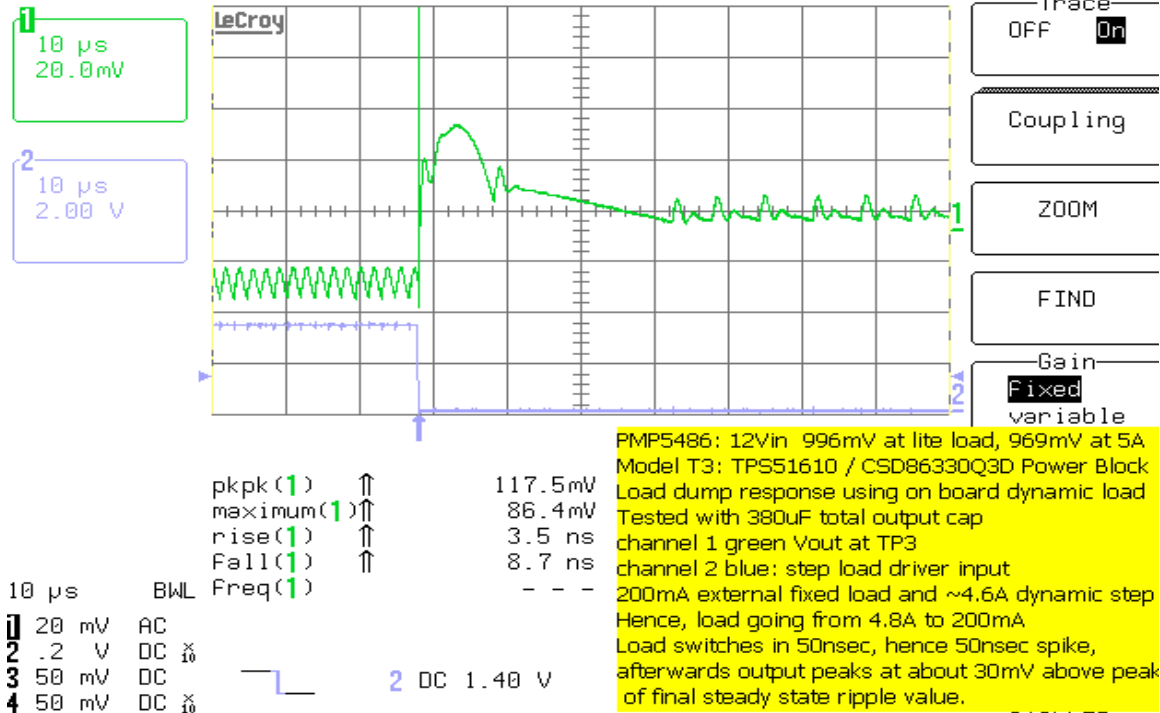
Load step response: model T3: 12Vin

22-Jun-10  
14:49:25



Load dump response: Model T3

22-Jun-10  
14:54:04



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